Appendix 3 Product End-of-Life Disassembly instructions

Product Identification:

Marketing Name / Model	Description
MSA50	1U Small Form Factor SAS JBOD

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment.

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product.
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 square cm	5 (1 in each pwr sply, 3 in main system)
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 square cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB / PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		2 (1 in each power supply)
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0

Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

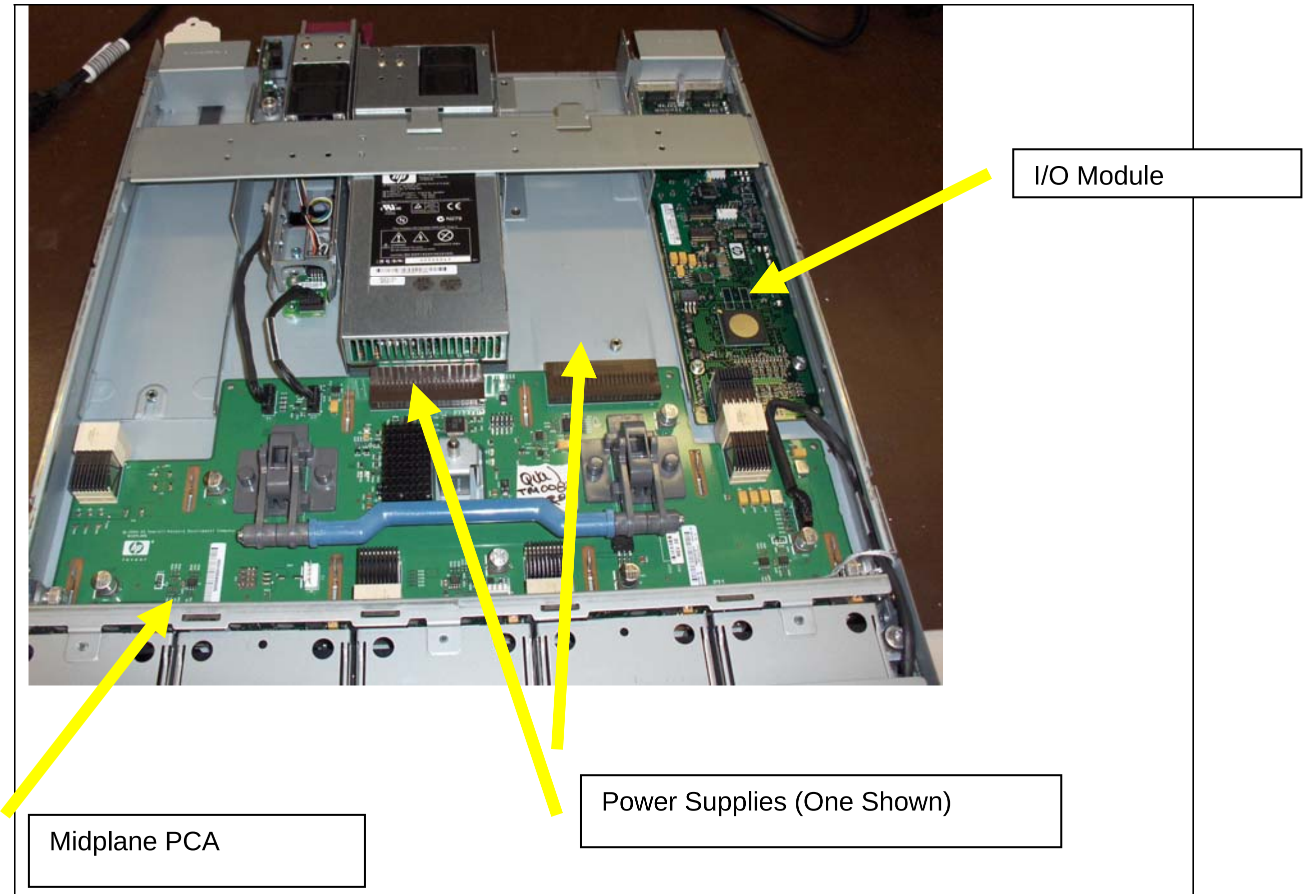
Tool Description	**Tool Size (if applicable)**
Phillips	For power supply
Torx	T-15

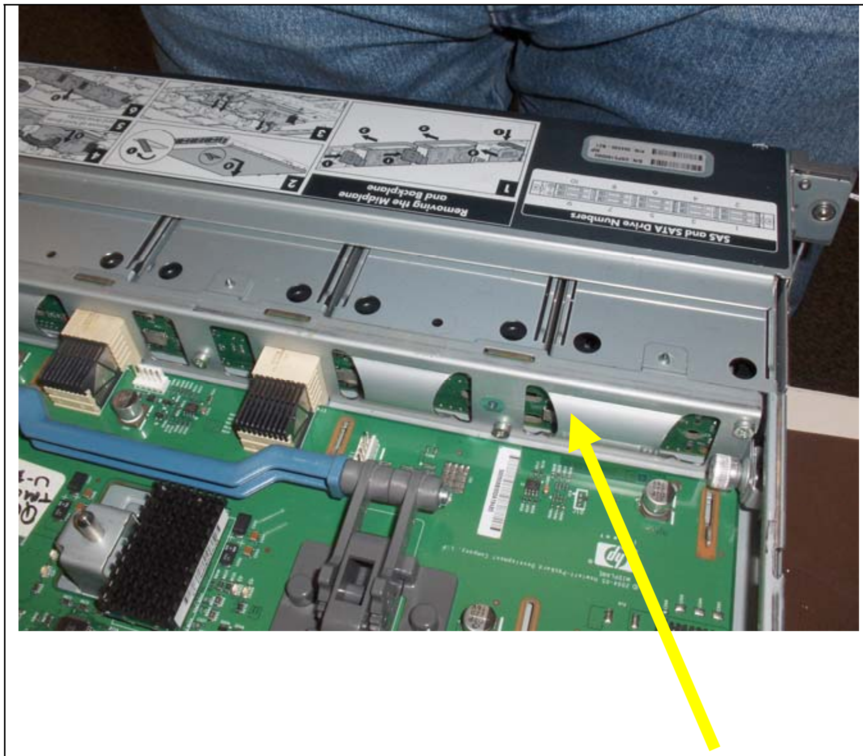
3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1	Remove cover and any hard drives installed.
2	Remove I/O module, midplane PCA, backplane and power supplies (See attachment 1 and 2)
3	2.5 CM capacitors: Remove power supplies and open with a Phillips screw driver. Remove the circuit board and pry the caps from the PCB with a flat blade screwdriver.(See attachment 3)
4	
5	

3.2 OPTIONAL: Depending upon the complexity of the disassembly process, a graphic depicting the locations of items contained within the product which require selective treatment (with descriptions and arrows identifying locations) can be inserted below:


I/O Module
Power Supplies (One Shown)
Midplane PCA


Removing the Midplane and Backplane
SAS and SATA Drive Numbers

Backplane

Remove capacitor